



## N-Channel 60-V (D-S) MOSFET

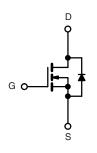
| PRODUCT SUMMARY     |                                 |                    |                       |  |
|---------------------|---------------------------------|--------------------|-----------------------|--|
| V <sub>DS</sub> (V) | $R_{DS(on)}(\Omega)$            | I <sub>D</sub> (A) | Q <sub>g</sub> (Typ.) |  |
| 60                  | 0.006 at V <sub>GS</sub> = 10 V | 90 <sup>d</sup>    | 78.5                  |  |

#### **FEATURES**

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- 100 %  $R_g$  and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

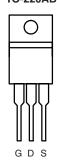
## **APPLICATIONS**

- Power Supply
  - Secondary Synchronous Rectification
- Industrial



N-Channel MOSFET

#### **TO-220AB**



Top View

Ordering Information: SUP90N06-6m0P-E3 (Lead (Pb)-free)

| <b>ABSOLUTE MAXIMUM RATINGS</b>                     | T <sub>C</sub> = 25 °C, unless oth  | erwise noted                      |                  | •        |
|---|-------------------------------------|-----------------------------------|------------------|----------|
| Parameter   | Symbol                              | Limit                             | Unit             |          |
| Drain-Source Voltage                                | V <sub>DS</sub>                     | 60                                | V                |          |
| Gate-Source Voltage                                 | V <sub>GS</sub>                     | ± 20                              | 7 °              |          |
| Continuous Drain Current (T <sub>.1</sub> = 175 °C) | T <sub>C</sub> = 25 °C              | I-                                | 90 <sup>d</sup>  |          |
| Continuous Diam Current (1) = 175 C)                | T <sub>C</sub> = 70 °C              | I <sub>D</sub>                    | 90 <sup>d</sup>  | <b>1</b> |
| Pulsed Drain Current                                | I <sub>DM</sub>                     | 240                               | A                |          |
| Avalanche Current                                   | I <sub>AS</sub>                     | 50                                |                  |          |
| Single Avalanche Energy <sup>a</sup>                | L = 0.1 mH                          | E <sub>AS</sub>                   | 125              | mJ       |
| Mariana Barra Biraira iland                         | T <sub>C</sub> = 25 °C              | В                                 | 272 <sup>b</sup> | 10/      |
| Maximum Power Dissipation <sup>a</sup>              | T <sub>A</sub> = 25 °C <sup>c</sup> | P <sub>D</sub>                    | 3.75             | W        |
| Operating Junction and Storage Temperature Range    |                                     | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175      | °C       |

| THERMAL RESISTANCE RATINGS                   |                   |       |      |  |  |
|--|-------------------|-------|------|--|--|
| Parameter                                    | Symbol            | Limit | Unit |  |  |
| Junction-to-Ambient (PCB Mount) <sup>c</sup> | R <sub>thJA</sub> | 40    | °C/W |  |  |
| Junction-to-Case (Drain)                     | R <sub>thJC</sub> | 0.55  | C/VV |  |  |

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.c. When Mounted on 1" square PCB (FR-4 material).
- d. Package limited.

## SUP90N06-6m0P

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| Parameter                                     | Symbol               | Test Conditions  | Min. | Тур.  | Max.  | Unit    |  |
|---|----------------------|--|------|-------|-------|---------|--|
| Static  |                      |  |      |       |       |         |  |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>      | $V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$                        | 60   |       | V     |         |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}, I_D = 250 \mu A$                                     | 2.5  |       | 4.5   | 7 V     |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>     | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$                      |      |       | ± 250 | nA      |  |
|   |                      | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V                          |      |       | 1     |         |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>     | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C |      |       | 50    | μΑ      |  |
|   |                      | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C |      |       | 250   |         |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>   | $V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$                       | 70   |       |       | Α       |  |
| D : 0   | D                    | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A                          |      | 0.005 | 0.006 | Ω       |  |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C |      | 0.008 | 0.010 |         |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>      | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A                          |      | 58    |       | S       |  |
| Dynamic <sup>b</sup>                          | •                    |  |      |       |       |         |  |
| Input Capacitance                             | C <sub>iss</sub>     |  |      | 4700  |       |         |  |
| Output Capacitance                            | C <sub>oss</sub>     | $V_{GS} = 0 \text{ V}, V_{DS} = 30 \text{ V}, f = 1 \text{ MHz}$       |      | 620   |       | pF      |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>     |  |      | 250   |       |         |  |
| Total Gate Charge <sup>c</sup>                | $Q_g$                |  |      | 78.5  | 120   |         |  |
| Gate-Source Charge <sup>c</sup>               | $Q_{gs}$             | $V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$   |      | 28    |       | nC      |  |
| Gate-Drain Charge <sup>c</sup>                | $Q_{gd}$             |  |      | 20.6  |       |         |  |
| Gate Resistance                               | R <sub>g</sub>       | f = 1 MHz  |      | 1.2   | 2.4   | Ω       |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>   |  |      | 16    | 30    |         |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>       | $V_{DD} = 30 \text{ V}, R_{L} = 0.6 \Omega$                            |      | 10    | 20    | 20      |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>  | $I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$       |      | 25    | 40    | ns<br>- |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>       |  |      | 8     | 15    |         |  |
| Source-Drain Diode Ratings and Cha            | aracteristics        | T <sub>C</sub> = 25 °C <sup>b</sup>                                    |      |       |       |         |  |
| Continuous Current                            | I <sub>S</sub>       |  |      |       | 85    | _       |  |
| Pulsed Current                                | I <sub>SM</sub>      |  |      |       | 240   | Α       |  |
| Forward Voltage <sup>a</sup>                  | V <sub>SD</sub>      | $I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$                             |      | 0.83  | 1.5   | V       |  |
| Reverse Recovery Time                         | t <sub>rr</sub>      |  |      | 62    | 100   | ns      |  |
| Peak Reverse Recovery Current                 | I <sub>RM(REC)</sub> | I <sub>F</sub> = 75 A, dI/dt = 100 A/μs                                |      | 3.8   | 5.7   | Α       |  |
| Reverse Recovery Charge                       | Q <sub>rr</sub>      |  |      | 118   | 180   | nC      |  |

#### Notes:

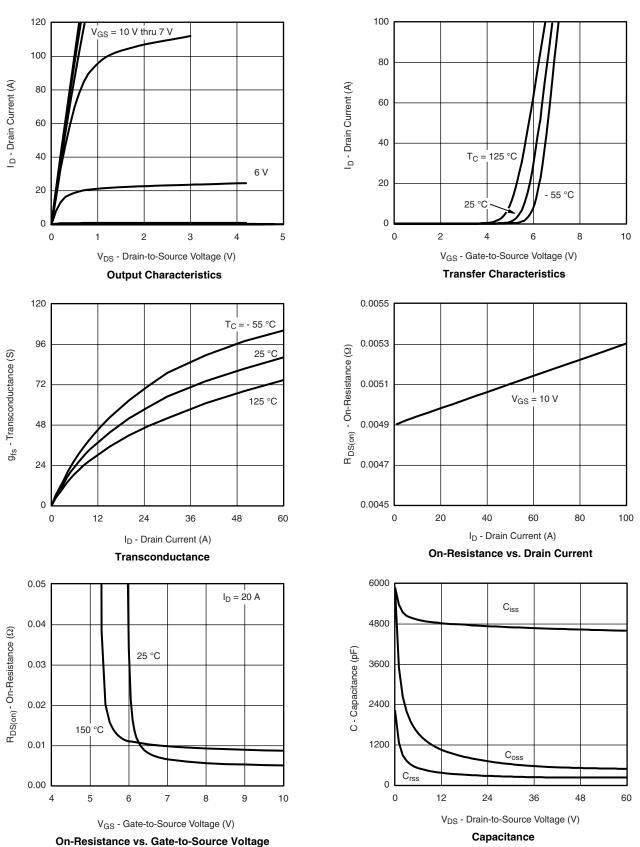
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





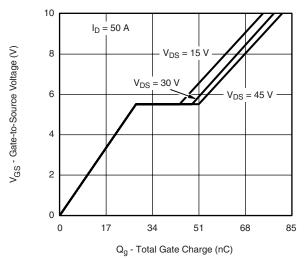
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



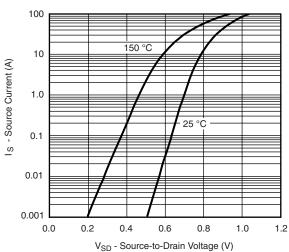
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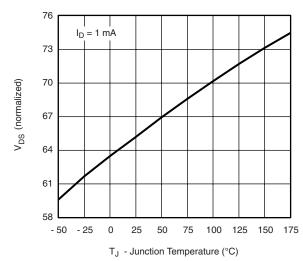
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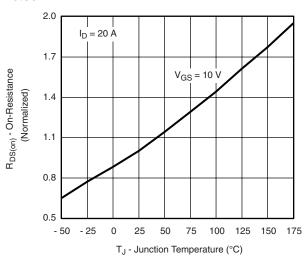
### On-Resistance vs. Junction Temperature



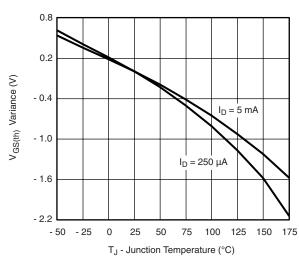
Gate Charge



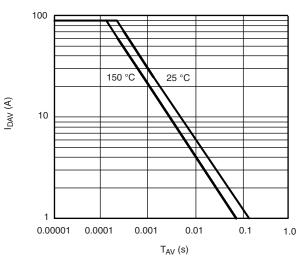
Source-Drain Diode Forward Voltage



Threshold Voltage



On-Resistance vs. Junction Temperature

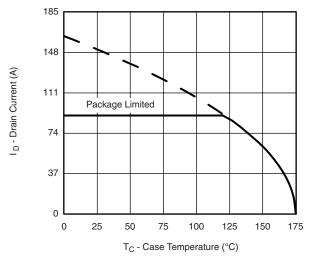


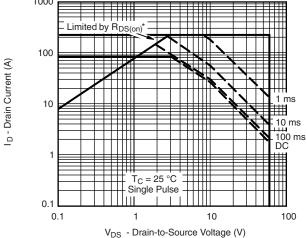
**Maximum Drain Current vs. Case Temperature** 



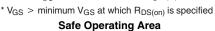
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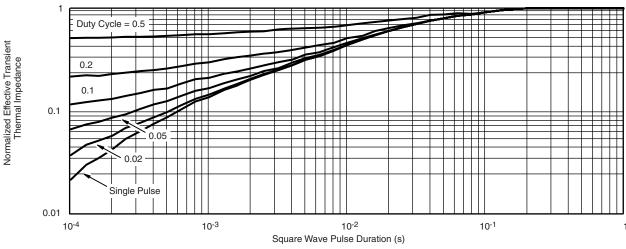
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Single Pulse Avalanche Current Capability vs. Time





Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?69536">www.vishay.com/ppg?69536</a>.



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## **TO-220AB**



|  | D2 |
|--|----|
|  |    |
|  |    |

|  | MILLIMETERS |       | INCHES |       |
|--|-------------|-------|--------|-------|
| DIM.   | MIN.        | MAX.  | MIN.   | MAX.  |
| А  | 4.25        | 4.65  | 0.167  | 0.183 |
| b  | 0.69        | 1.01  | 0.027  | 0.040 |
| b(1)   | 1.20        | 1.73  | 0.047  | 0.068 |
| С  | 0.36        | 0.61  | 0.014  | 0.024 |
| D  | 14.85       | 15.49 | 0.585  | 0.610 |
| D2   | 12.19       | 12.70 | 0.480  | 0.500 |
| Е  | 10.04       | 10.51 | 0.395  | 0.414 |
| е  | 2.41        | 2.67  | 0.095  | 0.105 |
| e(1)   | 4.88        | 5.28  | 0.192  | 0.208 |
| F  | 1.14        | 1.40  | 0.045  | 0.055 |
| H(1)   | 6.09        | 6.48  | 0.240  | 0.255 |
| J(1)   | 2.41        | 2.92  | 0.095  | 0.115 |
| L  | 13.35       | 14.02 | 0.526  | 0.552 |
| L(1)   | 3.32        | 3.82  | 0.131  | 0.150 |
| ØΡ   | 3.54        | 3.94  | 0.139  | 0.155 |
| Q  | 2.60        | 3.00  | 0.102  | 0.118 |
| ECN: T14-0413-Rev. P, 16-Jun-14<br>DWG: 5471 |             |       |        |       |

#### Note

 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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